# Onsemi

## Low-Voltage Dual-Supply 8-Bit Voltage Translator with Configurable Voltage **Supplies and Signal Levels, 3-State Outputs, and Auto Direction Sensing**

**FXLA108** 

#### Description

The FXLA108 is a configurable dual-voltage supply translator for both uni-directional and bi-directional voltage translation between two logic levels. The device allows translation between voltages as high as 3.6 V to as low as 1.1 V. The A port tracks the V<sub>CCA</sub> level and the B port tracks the V<sub>CCB</sub> level. This allows for bi-directional voltage translation over a variety of voltage levels: 1.2 V, 1.5 V, 1.8 V, 2.5 V, and 3.3 V.

The device remains in three-state as long as either  $V_{CC} = 0$  V, allowing either V<sub>CC</sub> to be powered up first. Internal power-down control circuits place the device in 3-state if either V<sub>CC</sub> is removed.

The /OE input, when HIGH, disables both the A and B ports by placing them in a 3-state condition. The /OE input is supplied by VCCA.

The FXLA108 supports bi-directional translation without the need for a direction control pin. The two ports of the device have auto-direction sense capability. Either port may sense an input signal and transfer it as an output signal to the other port.

#### Features

- Bi-Directional Interface Between Two Levels: from 1.1 V to 3.6 V
- Fully Configurable: Inputs and Outputs Track V<sub>CC</sub>
- Non-Preferential Power-Up; Either V<sub>CC</sub> May Be Powered Up First
- Outputs Switch to 3–State if Either V<sub>CC</sub> is at GND
- Power–Off Protection
- Bus-Hold on Data Inputs Eliminates the Need for Pull-Up Resistors; Do Not Use Pull-Up Resistors on A or B Ports
- Control Input (/OE) Referenced to V<sub>CCA</sub> Voltage
- Packaged in 20-Terminal DQFN (2.5 mm x 4.5 mm)
- Direction Control Not Necessary
- 100 Mbps Throughput when Translating Between 1.8 V and 2.5 V
- ESD Protection Exceeds:
  - 8 kV HBM (per JESD22–A114 &Mil Std 883e 3015.7)
  - 2 kV CDM (per ESD STM 5.3)
- This is a Pb–Free Device

#### Applications

- Laptops, Notebooks
- Routers, Switches

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WQFN20 4.5x2.5, 0.5P CASE 510CD

#### MARKING DIAGRAM

	\$Y&Z&2&K FXLA108
= Logo	

= Assembly Plant Code

\$Y &Z

- = 2-Digit Date Code
- &2 &K = 2-Digits Lot Run Traceability Code
- FXLA108 = Specific Device Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 15 of this data sheet.

## **PIN CONFIGURATION**

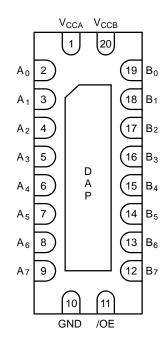


Figure 1. Pin Configuration (Top Through View)

#### **PIN DEFINITIONS**

Pin No.	Name	Description
1	V <sub>CCA</sub>	A-Side Power Supply
2	A <sub>0</sub>	A-Side Inputs or 3-State Outputs
3	A <sub>1</sub>	A-Side Inputs or 3-State Outputs
4	A <sub>2</sub>	A-Side Inputs or 3-State Outputs
5	A <sub>3</sub>	A-Side Inputs or 3-State Outputs
6	A <sub>4</sub>	A-Side Inputs or 3-State Outputs
7	A <sub>5</sub>	A-Side Inputs or 3-State Outputs
8	A <sub>6</sub>	A-Side Inputs or 3-State Outputs
9	A <sub>7</sub>	A-Side Inputs or 3-State Outputs
10	GND	Ground
11	/OE	Output Enable Input
12	B <sub>7</sub>	B-Side Inputs or 3-State Outputs
13	B <sub>6</sub>	B-Side Inputs or 3-State Outputs
14	B <sub>5</sub>	B-Side Inputs or 3-State Outputs
15	B <sub>4</sub>	B-Side Inputs or 3-State Outputs
16	B <sub>3</sub>	B-Side Inputs or 3-State Outputs
17	B <sub>2</sub>	B-Side Inputs or 3-State Outputs
18	B <sub>1</sub>	B-Side Inputs or 3-State Outputs
19	B <sub>0</sub>	B-Side Inputs or 3-State Outputs
20	V <sub>CCB</sub>	B-Side Power Supply
DAP	NC	No Connect

## FUNCTIONAL DIAGRAM

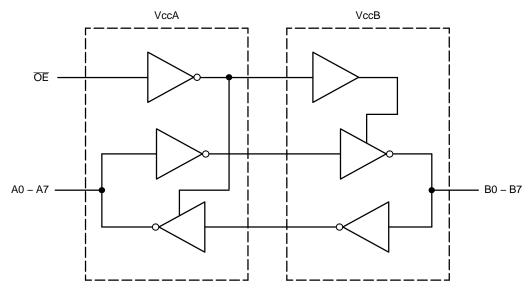


Figure 2. Functional Diagram

#### FUNCTION TABLE

Control	
/OE	Outputs
LOW Logic Level	Normal Operation
HIGH Logic Level	3-State

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	V <sub>CCA</sub>	-0.5	4.6	V
		V <sub>CCB</sub>	-0.5	4.6	
VI	DC Input Voltage	I/O Ports A and B	-0.5	4.6	V
		Control Input (/OE)	-0.5	4.6	
Vo	Output Voltage (Note 2)	Output 3–State	-0.5	4.6	V
		Output Active (A <sub>n</sub> )	-0.5	V <sub>CCA</sub> + 0.5	
		Output Active (B <sub>n</sub> )	-0.5	V <sub>CCB</sub> + 0.5	
I <sub>IK</sub>	DC Input Diode Current	V <sub>1</sub> < 0 V	-	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>O</sub> < 0 V	-	-50	mA
		$V_{O} > V_{CC}$	-	+50	
I <sub>OH</sub> /I <sub>OL</sub>	DC Output Source/Sink Current	<u>.</u>	-50	+50	mA
I <sub>CC</sub>	DC $V_{CC}$ or Ground Current (Per Suppl	y Pin)	-	±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
PD	Power Dissipation		-	35	mW
ESD	Human Body Model, JESD22-A114		-	8	kV
	Charged Device Model, JESD22-C10	1	-	2	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. I<sub>O</sub> absolute maximum ratings must be observed.
2. All unused inputs and input/outputs must be held at V<sub>CCi</sub> or GND.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Power Supply	Operating $V_{CCA}$ or $V_{CCB}$	1.1	3.6	V
V <sub>IN</sub>	Input Voltage	Ports A and B	0	3.6	V
		Control Input (/OE)	0	V <sub>CCA</sub>	V
T <sub>A</sub>	Operating Temperature, Free Air		-40	+85	°C
dt/dV	Minimum Input Edge Rate	V <sub>CCA/B</sub> = 1.1 to 3.6 V	-	10	ns/V
$\Theta_{JA}$	Thermal Resistance: Junction-to-Ambient		-	50	°C/W
Θ <sub>JC</sub>	Thermal Resistance: Junction-to-Case		-	23	°C/W

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

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#### POWER-UP/POWER-DOWN SEQUENCE

FXL translators offer an advantage in that either  $V_{CC}$  may be powered up first. This benefit derives from the chip design. When either  $V_{CC}$  is at 0 V, outputs are in a high–impedance state. The control input (/OE) is designed to track the  $V_{CCA}$  supply. A pull–up resistor tying /OE to  $V_{CCA}$  should be used to ensure that bus contention, excessive currents, or oscillations do not occur during power–up or power–down. The size of the pull–up resistor is based upon the current–sinking capability of the device driving the /OE pin.

The recommended power-up sequence is:

- 1. Apply power to the first  $V_{CC}$ .
- 2. Apply power to the second  $V_{CC}$ .
- 3. Drive the /OE input LOW to enable the device.

- The recommended power-down sequence is:
  - 1. Drive /OE input HIGH to disable the device.
  - 2. Remove power from either  $V_{CC}$ .
  - 3. Remove power from other  $V_{CC.}$

#### Pull-Up/Pull-Down Resistors

<u>Do not use pull–up or pull–down resistors</u>. This device has bus–hold circuits: pull–up or pull–down resistors are not recommended because they interfere with the output state. The current through these resistors may exceed the hold drive,  $I_{I(HOLD)}$  and/or  $I_{I(OD)}$  bus–hold currents. The bus–hold feature eliminates the need for extra resistors.

Symbol	Parameter	Conditions	V <sub>CCA</sub> (V)	V <sub>CCB</sub> (V)	Min	Тур	Max	Unit
V <sub>IHA</sub>	High-Level Input Voltage	Data Inputs An Control	2.70 to 3.60	1.10 to 3.60	2.00	-	-	V
		Pin /OE	2.30 to 2.70		1.60	-	-	
			1.65 to 2.30		0.65 x V <sub>CCA</sub>	-	-	
			1.40 to 1.65		0.65 x V <sub>CCA</sub>	-	-	
			1.10 to 1.40		$0.9 \times V_{CCA}$	-	-	
V <sub>IHB</sub>		Data Inputs B <sub>n</sub>	1.10 to 3.60	2.70 to 3.60	2.00	-	-	V
				2.30 to 2.70	1.60	-	-	
				1.65 to 2.30	0.65 x V <sub>CCB</sub>	-	-	
				1.40 to 1.65	0.65 x V <sub>CCB</sub>	-	-	
				1.10 to 1.40	$0.9 \times V_{CCB}$	-	-	
V <sub>ILA</sub>	Low-Level Input Voltage	Data Inputs An Control	2.70 to 3.60	1.10 to 3.60	_	-	0.8	V
		Pin /OE	2.30 to 2.70		_	-	0.7	
			1.65 to 2.30		_	-	0.35 x V <sub>CCA</sub>	
			1.40 to 1.65		_	-	0.35 x V <sub>CCA</sub>	
			1.10 to 1.40		-	-	0.1 x V <sub>CCA</sub>	
V <sub>ILB</sub>		Data Inputs B <sub>n</sub>	1.10 to 3.60	2.70 to 3.60	-	_	0.8	V
				2.30 to 2.70	-	_	0.7	
				1.65 to 2.30	-	_	0.35 x V <sub>CCB</sub>	
				1.40 to 1.65	-	_	0.35 x V <sub>CCB</sub>	
				1.10 to 1.40	-	_	0.1 x V <sub>CCB</sub>	
V <sub>OHA</sub>	High-Level Output Voltage	I <sub>OH</sub> = -4 μA	1.10 to 3.60	1.10 to 3.60	V <sub>CCA</sub> – 0.4	_	-	V
V <sub>OHB</sub>	(Note 3)	I <sub>OH</sub> = -4 μA	1.10 to 3.60	1.10 to 3.60	V <sub>CCB</sub> – 0.4	_	-	
V <sub>OLA</sub>	Low-Level Output Voltage	I <sub>OL</sub> = 4 μA	1.10 to 3.60	1.10 to 3.60	_	_	0.4	V
V <sub>OLB</sub>	(Note 3)	I <sub>OL</sub> = 4 μA	1.10 to 3.60	1.10 to 3.60	-	_	0.4	
I <sub>I(HOLD)</sub>	Bus-Hold Input Minimum	V <sub>IN</sub> = 0.80 V	3.00	3.00	75.0	-	-	μA
	Drive Current	V <sub>IN</sub> = 2.00 V	3.00	3.00	-75.0	-	-	
		V <sub>IN</sub> = 0.7 V	2.30	2.30	45.0	-	-	
		V <sub>IN</sub> = 1.60 V	2.30	2.30	-45.0	_	-	
		V <sub>IN</sub> = 0.57 V	1.65	1.65	25.0	-	-	
		V <sub>IN</sub> = 1.07 V	1.65	1.65	-25.0	-	-	
		V <sub>IN</sub> = 0.49 V	1.40	1.40	11.0	_	-	
		V <sub>IN</sub> = 0.91 V	1.40	1.40	-11.0	-	_	
		V <sub>IN</sub> = 0.11 V	1.10	1.10	_	4.0	_	
		V <sub>IN</sub> = 0.99 V	1.10	1.10	-	-4.0	-	
I <sub>I(ODH)</sub>	Bus-Hold Input Overdrive	Data Inputs A <sub>n</sub> , B <sub>n</sub>	3.60	3.60	450.00	-	-	μA
· /	High Current (Note 4)		2.70	2.70	300.00	_	_	
			1.95	1.95	200.00	_	_	
			1.60	1.60	120.00	_	_	
			1.40	1.40	80.00	_	_	

## **DC CHARACTERISTICS** ( $T_A = -40$ to $85^{\circ}C$ )

Symbol	Parameter	Conditions	V <sub>CCA</sub> (V)	V <sub>CCB</sub> (V)	Min	Тур	Max	Unit
I <sub>I(ODL)</sub>	Bus-Hold Input Overdrive	Data Inputs A <sub>n</sub> , B <sub>n</sub>	3.60	3.60	-450.00	-	-	μΑ
	Low Current (Note 5)		2.70	2.70	-300.00	-	-	1
			1.95	1.95	-200.00	-	-	1
			1.60	1.60	-120.00	-	-	
			1.40	1.40	-80.00	-	-	
lı	Input Leakage Current	Control Inputs /OE, $V_I = V_{CCA}$ or GND	1.10 to 3.60	3.60	-	-	±1.0	μΑ
I <sub>OFF</sub>	Power–Off Leakage	$A_n V_0 = 0 V \text{ to } 3.6 V$	0	3.6	-	-	±2.0	μΑ
	Current	$B_n V_0 = 0 V \text{ to } 3.6 V$	3.60	0	-	-	±2.0	1
I <sub>OZ</sub>	3-State Output Leakage	A <sub>n</sub> , B <sub>n</sub> V <sub>O</sub> = 0 V or 3.6 V, /OE = V <sub>IH</sub>	3.6	3.60	_	-	±5.0	μΑ
		$A_n V_O = 0 V \text{ or } 3.6 V,$ /OE = GND	3.60	0	_	-	±5.0	
		$B_n V_0 = 0 V \text{ or } 3.6 V,$ /OE = GND	0	3.60	_	-	±5.0	
I <sub>CCA/B</sub>	Quiescent Supply Current (Note 6, 7)	$V_{I} = V_{CCI}$ or GND; $I_{O} = 0$ , /OE = GND	1.10 to 3.60	1.10 to 3.60	_	-	10.0	μΑ
I <sub>CCZ</sub>		$V_{I} = V_{CCI}$ or GND; $I_{O} = 0$ , /OE = $V_{IH}$	1.10 to 3.60	1.10 to 3.60	_	-	10.0	μΑ
I <sub>CCA</sub>	Quiescent Supply Current	$V_I = V_{CCB}$ or GND; $I_O = 0$ B-to-A Direction, /OE = GND	0	1.10 to 3.60	-	-	-10.0	μΑ
		$V_I = V_{CCA}$ or GND; $I_O = 0$ A-to-B Direction	1.10 to 3.60	0	_	-	10.0	
I <sub>CCB</sub>		$\label{eq:VI} \begin{array}{l} V_{I} = V_{CCA} \text{ or } GND; \ I_{O} = 0, \\ A-to-B \ Direction, \\ /OE = GND \end{array}$	1.10 to 3.60	0	-	-	-10.0	μΑ
		$V_I = V_{CCB}$ or GND; $I_O = 0$ B-to-A Direction	0	1.10 to 3.60	-	-	10.0	

#### DC CHARACTERISTICS (T<sub>A</sub> = -40 to $85^{\circ}$ C) (continued)

This is the output voltage for static conditions. Dynamic drive specifications are given in the Dynamic Output Electrical Characteristics table.
 An external drive must source at least the specified current to switch LOW-to-HIGH.

5. An external drive must source at least the specified current to switch HIGH-to-LOW. 6.  $V_{CCI}$  is the  $V_{CC}$  associated with the input side. 7. Reflects current per supply,  $V_{CCA}$  or  $V_{CCB}$ .

#### DYNAMIC OUTPUT ELECTRICAL CHARACTERISTICS

		to 3.6 V			V <sub>CCA</sub> = 2.3 V to 2.7 V		V <sub>CCA</sub> = 1.65 V to 1.95 V		: 1.4 V .6 V	V <sub>CCA</sub> = 1.1 V to 1.3 V	
Symbol	Parameter	Тур	Max	Тур	Max	Тур	Max	Тур	Max	Тур	Unit

A PORT (A<sub>n</sub>) OUTPUT LOAD: C<sub>L</sub> = 15 pF, R<sub>L</sub>  $\ge$  1 M $\Omega$  (C<sub>I/O</sub> = 4 pF), T<sub>A</sub> = -40 to 85°C

t <sub>rise</sub>	Output Rise Time A Port (Note 9)	-	3.0	_	3.5	_	4.0	_	5.0	7.5	ns
t <sub>fall</sub>	Output Fall Time A Port (Note 10)	-	3.0	-	3.5	-	4.0	-	5.0	7.5	ns
I <sub>OHD</sub>	Dynamic Output Current High (Note 9)	-11.4	1	-7.5	1	-4.7	-	-3.2	-	-1.7	mA
I <sub>OLD</sub>	Dynamic Output Current Low (Note 10)	+11.4	-	+7.5	1	+4.7	-	+3.2	-	+1.7	mA

B PORT (B<sub>n</sub>) OUTPUT LOAD: C<sub>L</sub> = 15 pF, R<sub>L</sub>  $\ge$  1 M $\Omega$  (C<sub>I/O</sub> = 5 pF), T<sub>A</sub> = -40 to 85°C

t <sub>rise</sub>	Output Rise Time B Port (Note 9)	-	3.0	-	3.5	-	4.0	-	5.0	7.5	ns
t <sub>fall</sub>	Output Fall Time B Port (Note 10)	-	3.0	-	3.5	-	4.0	-	5.0	7.5	ns
I <sub>OHD</sub>	Dynamic Output Current High (Note 9)	-12.0	-	-7.9	-	-5.0	-	-3.4	-	-1.8	mA
I <sub>OLD</sub>	Dynamic Output Current Low (Note 10)	+12.0	-	+7.9	-	+5.0	-	+3.4	-	+1.8	mA

Bynamic output characteristics are guaranteed, but not tested.
 See Figure 7.
 See Figure 8.

#### **AC CHARACTERISTICS**

		V <sub>CCB</sub> = to 3	= 3.0 V 5.6 V	V <sub>CCB</sub> = to 2	= 2.3 V .7 V	V <sub>CCB</sub> = to 1.	: 1.65 V 95 V	V <sub>CCB</sub> = to 1	= 1.4 V .6 V	V <sub>CCB</sub> = 1.1 V to 1.3 V	
Symbol	Parameter	Тур	Max	Тур	Max	Тур	Max	Тур	Мах	Тур	Unit
V <sub>CCA</sub> = 3.0	V to 3.6 V, $T_A = -40$ to 85°C										-
t <sub>PLH</sub> , t <sub>PHL</sub>	A to B	0.2	4.0	0.3	4.2	0.5	5.4	0.6	6.8	6.9	ns
	B to A	0.2	4.0	0.2	4.1	0.3	5.0	0.5	6.0	4.5	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	/OE to A, /OE to B	-	1.7	-	1.7	-	1.7	-	1.7	1.7	μs
t <sub>SKEW</sub>	A Port, B Port (Note 11)	-	0.5	-	0.5	-	0.5	-	1.0	1.0	ns
V <sub>CCA</sub> = 2.3	V to 2.7 V, $T_A = -40$ to 85°C		-	-	-	-			-		
t <sub>PLH</sub> , t <sub>PHL</sub>	A to B	0.2	4.1	0.4	4.5	0.5	5.6	0.8	6.9	7.0	ns
	B to A	0.3	4.2	0.4	4.5	0.5	5.5	0.5	6.5	4.8	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	/OE to A, /OE to B	-	1.7	-	1.7	-	1.7	-	1.7	1.7	μs
t <sub>SKEW</sub>	A Port, B Port (Note 11)	-	0.5	-	0.5	-	0.5	-	1.0	1.0	ns
V <sub>CCA</sub> = 1.6	5 V to 1.95 V, T <sub>A</sub> = −40 to 85°0	с <sup>і</sup>									
t <sub>PLH</sub> , t <sub>PHL</sub>	A to B	0.3	5.0	0.5	5.5	0.8	6.7	0.9	7.5	7.5	ns
	B to A	0.5	5.4	0.5	5.6	0.8	6.7	1.0	7.0	5.4	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	/OE to A, /OE to B	-	1.7	-	1.7	-	1.7	-	1.7	1.7	μs
t <sub>SKEW</sub>	A Port, B Port (Note 11)	-	0.5	-	0.5	-	0.5	-	1.0	1.0	ns
V <sub>CCA</sub> = 1.4	V to 1.6 V, T <sub>A</sub> = -40 to 85°C										
t <sub>PLH</sub> , t <sub>PHL</sub>	A to B	0.5	6.0	0.5	6.5	1.0	7.0	1.0	8.5	7.9	ns
	B to A	0.6	6.8	0.8	6.9	0.9	7.5	1.0	8.5	6.1	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	/OE to A, /OE to B	-	1.7	-	1.7	-	1.7	-	1.7	1.7	μs
t <sub>SKEW</sub>	A Port, B Port (Note 12)	-	1.0	-	1.0	-	1.0	-	1.0	1.0	ns
V <sub>CCA</sub> = 1.1	V to 1.3 V, T <sub>A</sub> = −40 to 85°C	•	•	-	•	•	•	•	•	•	•
		Ту	/p	Т	/p	Ту	ур	Ту	ур	Тур	
t <sub>PLH</sub> , t <sub>PHL</sub>	A to B	4	.6	4	.8	5	.4	6	.2	9.2	ns
	B to A	6	.8	7	.0	7	.4	7	.8	9.1	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	/OE to A, /OE to B	1	.7	1	.7	1	.7	1	.7	1.7	μS
t <sub>SKEW</sub>	A Port, B Port (Note 12)	1	.0	1	.0	1	.0	1	.0	1.0	ns

11. Skew is the variation of propagation delay between output signals and applies only to output signals on the same port (A<sub>n</sub> or B<sub>n</sub>) and switching with the same polarity (LOW-to-HIGH or HIGH-to-LOW) (see Figure 10). Skew is guaranteed, but not tested.

12. Skew is the variation of propagation delay between output signals and applies only to output signals on the same port (An or Bn) and switching with the same polarity (LOW-to-HIGH or HIGH-to-LOW) (see Figure 10). Skew is guaranteed, but not tested.

#### MAXIMUM DATA RATE (T<sub>A</sub> = -40 to $85^{\circ}$ C)

	V <sub>CCB</sub> = 3.0 V to 3.6 V	V <sub>CCB</sub> = 2.3 V to 2.7 V	V <sub>CCB</sub> = 1.65 V to 1.95 V	V <sub>CCB</sub> = 1.4 V to 1.6 V	V <sub>CCB</sub> = 1.1 V to 1.3 V	
V <sub>CCA</sub>	Min	Min	Min	Min	Тур	Unit
$V_{CCA} = 3.00 \text{ V} \text{ to } 3.60 \text{ V}$	140	120	100	80	40	Mbps
$V_{CCA}$ = 2.30 V to 2.70 V	120	120	100	80	40	Mbps
V <sub>CCA</sub> = 1.65 V to 1.95 V	100	100	80	60	40	Mbps
V <sub>CCA</sub> = 1.40 V to 1.60 V	80	80	60	60	40	Mbps
	Тур	Тур	Тур	Тур	Тур	
V <sub>CCA</sub> = 1.10 V to 1.30 V	40	40	40	40	40	Mbps

Maximum data rate is guaranteed, but not tested.
 Maximum data rate is specified in megabits per second (see Figure 9). It is equivalent to two times the F-toggle frequency, specified in megahertz. For example, 100 Mbps is equivalent to 50 MHz.

#### CAPACITANCE

Symbol	Parameter		Conditions	T <sub>A</sub> = +25°C Typical	Unit
C <sub>IN</sub>	Input Capacitance Control Pin (/OE)		$V_{CCA} = V_{CCB} = GND$	3	pF
C <sub>I/O</sub>	Input/Output Capacitance	A <sub>n</sub>	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, /OE = V_{CCA}$	4	pF
		Bn		5	
C <sub>pd</sub>	Power Dissipation Capacitance		$V_{CCA}$ = $V_{CCB}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC},f$ = 10 MHz	25	pF

## **I/O ARCHITECTURE BENEFIT**

The FXLA108 I/O architecture benefits the end user, beyond level translation, in the following three ways:

Auto Direction without an external direction pin.

*Drive Capacitive Loads*. Automatically shifts to a higher current drive mode only during "Dynamic Mode" or HL / LH transitions.

*Lower Power Consumption*. Automatically shifts to low–power mode during "Static Mode" (no transitions), lowering power consumption.

The FXLA108 does not require a direction pin. Instead, the I/O architecture detects input transitions on both side and automatically transfers the data to the corresponding output. For example, for a given channel, if both A and B side are at a static LOW, the direction has been established as  $A \rightarrow B$ , and a LH transition occurs on the B port; the FXLA108 internal I/O architecture automatically changes direction from  $A \rightarrow B$  to  $B \rightarrow A$ .

During HL / LH transitions, or "Dynamic Mode," a strong output driver drives the output channel in parallel with a weak output driver. After a typical delay of approximately 10 ns - 50 ns, the strong driver is turned off, leaving the weak driver enabled for holding the logic state of the channel. This weak driver is called the "bus hold." "Static Mode" is when only the bus hold drives the channel. The bus hold can be over ridden in the event of a direction change. The strong driver allows the FXLA108 to quickly charge and discharge capacitive transmission lines during dynamic mode. Static mode conserves power, where  $I_{CC}$  is typically < 5  $\mu$ A.

#### **Bus Hold Minimum Drive Current**

Specifies the minimum amount of current the bus hold driver can source/sink. The bus hold minimum drive current (II<sub>HOLD</sub>) is  $V_{CC}$  dependent and guaranteed in the DC Electrical tables. The intent is to maintain a valid output state in a static mode, but that can be overridden when an input data transition occurs.

#### **Bus Hold Input Overdrive Drive Current**

Specifies the minimum amount of current required (by an external device) to overdrive the bus hold in the event of a direction change. The bus hold overdrive ( $II_{ODH}$ ,  $II_{ODL}$ ) is  $V_{CC}$  dependent and guaranteed in the DC Electrical tables.

#### **Dynamic Output Current**

The strength of the output driver during LH / HL transitions is *referenced on page 8*, *Dynamic Output Electrical Characteristics*, *I*<sub>OHD</sub>, and *I*<sub>OLD</sub>.

#### **TEST DIAGRAMS**

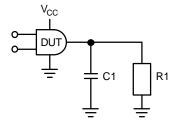


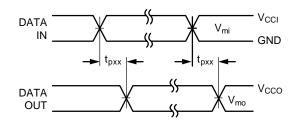
Figure 3. Test Circuit

#### Table 1. AC TEST CONDITIONS

Test	Input Signal	Output Enable Control
t <sub>PLH</sub> , t <sub>PHL</sub>	Data Pulses	0 V
t <sub>PZL</sub>	0 V	HIGH to LOW Switch
t <sub>PZH</sub>	V <sub>CCI</sub>	HIGH to LOW Switch

#### Table 2. AC LOAD

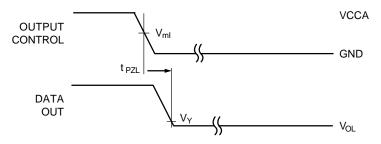
V <sub>CCo</sub>	C1	R1		
1.2 V ±0.1 V	15 pF	1 MΩ		
1.5 V ±0.1 V	15 pF	1 MΩ		
1.8 V ±0.15 V	15 pF	1 MΩ		
2.5 V ±0.2 V	15 pF	1 MΩ		
3.3 V ±0.3 V	15 pF	1 MΩ		



#### NOTES:

15. Input  $t_R = t_F = 2.0$  ns, 10% to 90%. 16. Input  $t_R = t_F = 2.5$  ns, 10% to 90%, at  $V_I = 3.0$  V to 3.6 V only.

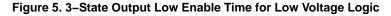
#### Figure 4. Waveform for Inverting and Non–Inverting Functions

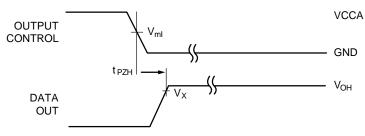


#### NOTES:

17. Input  $t_R = t_F = 2.0$  ns, 10% to 90%.

18. Input  $t_R$  =  $t_F$  = 2.5 ns, 10% to 90%, at  $V_I$  = 3.0 V to 3.6 V only.





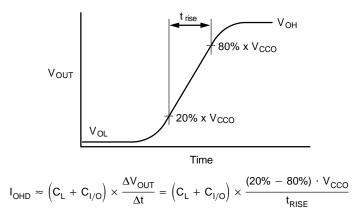
NOTES: 19. Input  $t_R = t_F = 2.0$  ns, 10% to 90%. 20. Input  $t_R = t_F = 2.5$  ns, 10% to 90%, at  $V_I = 3.0$  V to 3.6 V only.

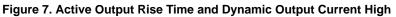
#### Figure 6. 3–State Output High Enable Time for Low Voltage Logic

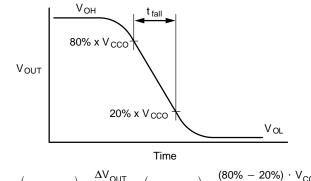
#### **Table 3. TEST MEASURE POINTS**

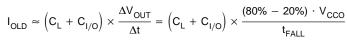
Symbol	V <sub>DD</sub>
V <sub>MI</sub> (Note 21)	V <sub>CCI</sub> / 2
V <sub>MO</sub>	V <sub>CCO</sub> / 2
V <sub>X</sub>	0.9 x V <sub>CCO</sub>
V <sub>Y</sub>	0.1 x V <sub>CCO</sub>

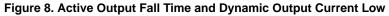
21.  $V_{CCI} = V_{CCA}$  for control pin /OE or  $V_{MI} = (V_{CCA} / 2)$ .

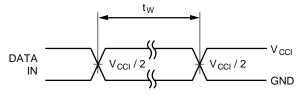






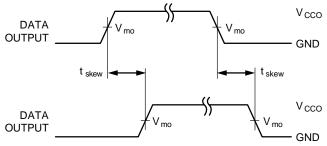






Maximum Data Rate,  $f = 1 / t_W$ 

Figure 9. Maximum Data Rate







#### **ORDERING INFORMATION**

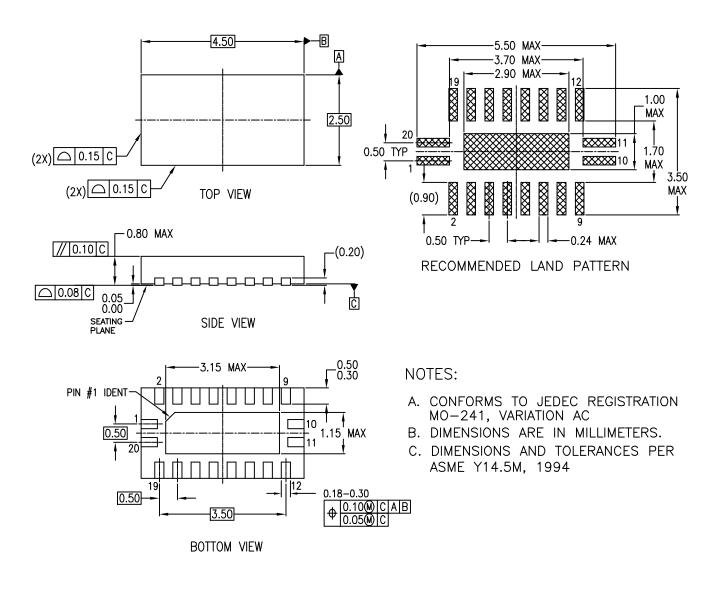
Part Number	Operating Temperature Range	Package	Shipping <sup>†</sup>
FXLA108BQX	−40 to 85°C	WQFN20 4.5x2.5, 0.5P 20–Terminal DQFN 2.5mm x 4.5mm Package (Pb–Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



WQFN20 4.5x2.5, 0.5P CASE 510CD ISSUE O

DATE 31 AUG 2016



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